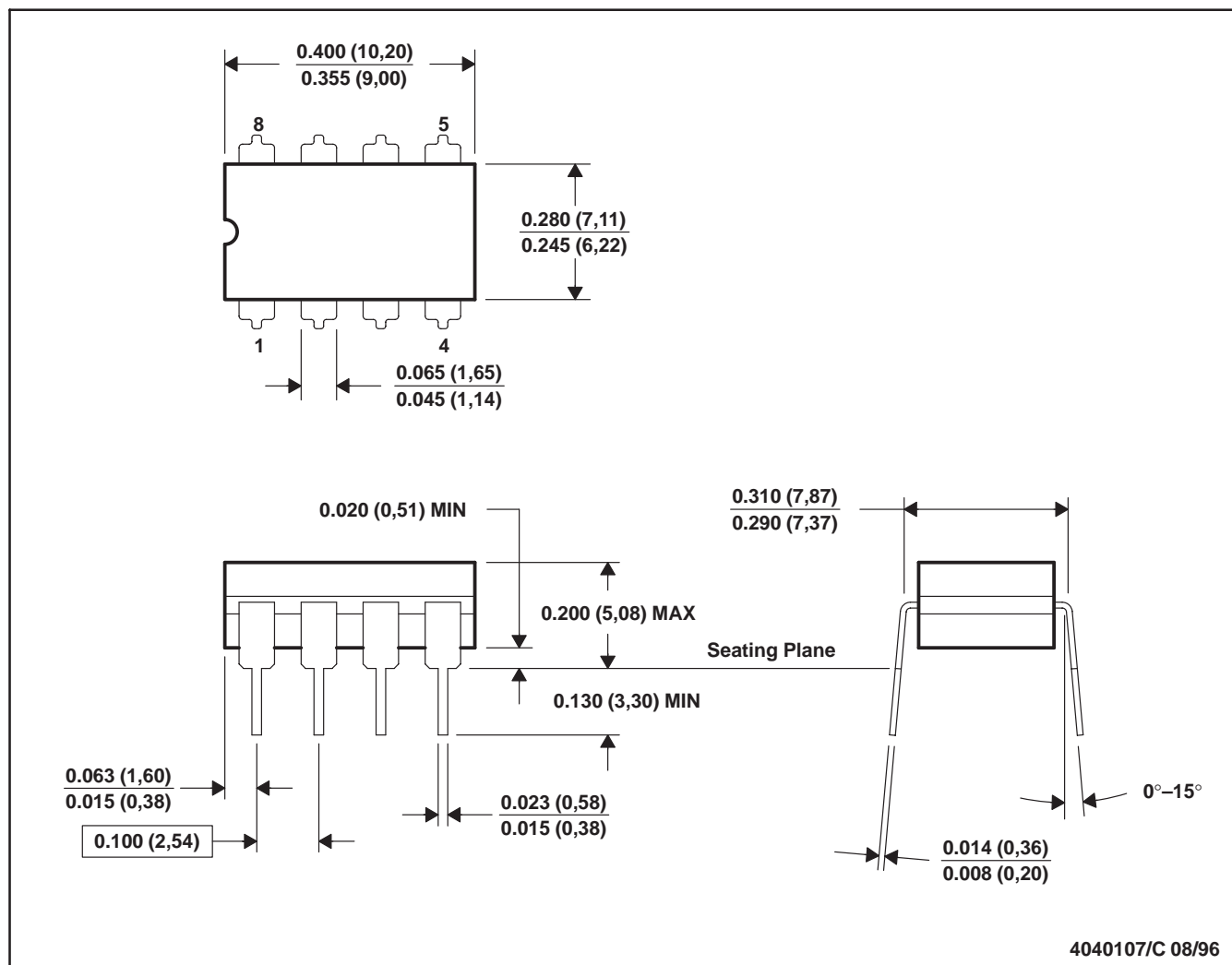


## JG (R-GDIP-T8)

## CERAMIC DUAL-IN-LINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL-STD-1835 GDIP1-T8

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